HIGH DENSITY COLUMN GRID ARRAY CONNECTIONS AND METHOD THEREOF

ABSTRACT

The present invention relates generally to a new semiconductor chip carrier connections, where the chip carrier (10) and the second level assembly are made by a surface mount technology. More particularly, the invention encompasses surface mount technologies, such as, Ball Grid Array (BGA), Column Grid Array (CGA), to name a few, where the surface mount technology comprises essentially of a non-solder metallic connection (23), such as, a copper connection. The present invention is also related to Column Grid Array structures and process thereof.

Fig. 1